



HY80N03

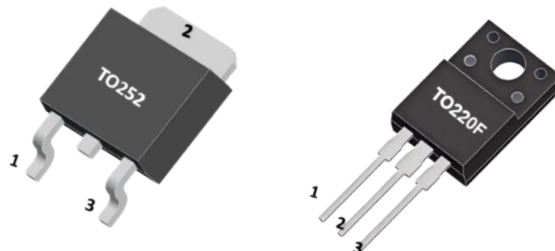
N-CHANNEL POWER MOSFET

80A, 30V N-CHANNEL ENHANCEMENT MODE POWER MOSFET

DESCRIPTION

The XD80N03Y uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

The XD80N03Y meet the ROHS and Green Product requirement with full function reliability approved.



FEATURE

- * High density cell design for ultra low $R_{DS(ON)}$
- * Fully characterized Avalanche voltage and current
- * Good stability and uniformity with high EAS
- * Excellent package for good heat dissipation
- * Special process technology for high ESD capability

APPLICATIONS

- * Power switching application
- * Hard switched and high frequency circuits
- * Uninterruptible Power Supply

MARKING



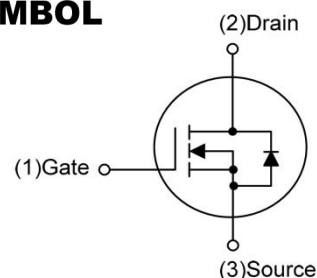
: HY LOGO

XD80N03Y=Device Code

XXXX=Date Code

Solid Dot=Green molding compound

SYMBOL



ABSOLUTE MAXIMUM RATINGS($T_A=25^{\circ}\text{C}$, unless otherwise specified.)

SYMBOL	PARAMETER		VALUE	UNIT
V _{DS}	Drain-Source Voltage		30	V
V _{GS}	Gate Source Voltage		±20	V
I _D	Continuous Drain Current (Note 1)		80	A
I _{DM}	Pulsed Drain Current (Note 2)		320	A
EAS	Single Pulsed Avalanche Energy(Note 3)		306	mJ
PD	Power Dissipation	TO-220F	70	W
		TO-252	83	
T _J	Storage Temperature		150	°C
T _{STG}	Thermal Resistance Fr .00m Junction To Ambient		-55~150	°C
T _L	Lead Temperature for Soldering Purposes(1/8" from case for 10s)		260	°C

Notes: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.



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■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-220F	θ_{JA}	62.5	°C/W
	TO-252		110	
Junction to Case	TO-220F	θ_{JC}	1.78	°C/W
	TO-252		1.9	

■ ELECTRICAL CHARACTERISTICS (TA=25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =30V, V _{GS} =0V			1	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V,			±100	nA
ON CHARACTERISTICS(Note 4)						
Static drain-source on-sate resistance	R _{DS(ON)}	V _{GS} =10V, I _D =40A	3.4	3.7	4.0	mΩ
		V _{GS} =4.6V, I _D =30A	5.5	6.3	7.0	
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} ,I _D =250μA	1.0	1.4	3.0	V
Forward transconductance	g _{FS}	V _{DS} =5V, I _D =24A	20			S
DYNAMIC PARAMETERS(Note 4 5)						
Input Capacitance	C _{ISS}	V _{GS} =0V,V _{DS} =15V f=1.0MHz		2160		pF
Output Capacitance	C _{OSS}			272		pF
Reverse Transfer Capacitance	C _{RSS}			264		pF
SWITCHING PARAMETERS(Note 4 5)						
Total gate charge	Q _g	V _{DS} =10V,V _{GS} =10V I _D =30A		44		nC
Gate-source charge	Q _{gs}			6		
Gate-drain charge	Q _{gd}			11		
Turn-On Delay Time	td(on)	V _{DD} =15V,I _D =30A V _{GS} =10V, R _G =2.7Ω		20		nS
Turn-On Rise time	tr			15		
Turn-Off Delay Time	td(off)			60		
Turn-Off Fall time	tr			10		



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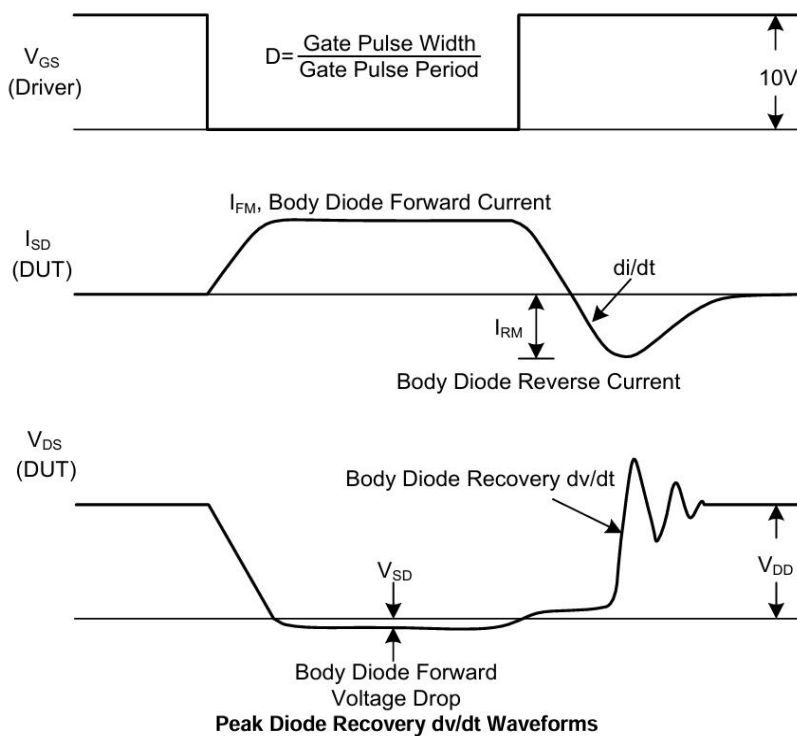
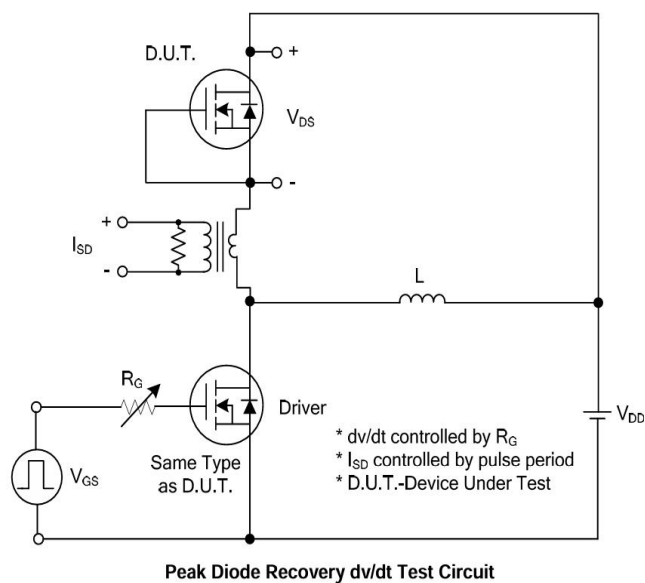
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Continuous drain-source diode forward current (Note 1)	IS				80	A
Pulsed drain-source diode forward current (Note 2)	ISM				320	A
Drain-source diode forward voltage(Note 4)	VSD	IS=24A,VGS=0V			1.2	V

Notes:

- 1.Tc=25℃ Limited only by maximum temperature allowed.
- 2.Pw≤10μs, Duty cycle≤1%.
- 3.EAS condition: VDD=30V,VGS=10V, L=0.5mH, Rg=25Ω Starting TJ = 25℃.
- 4.Pulse Test : Pulse Width≤300μs, duty cycle ≤2%.
- 5.Guaranteed by design, not subject to production.

■ TEST CIRCUITS AND WAVEFORMS

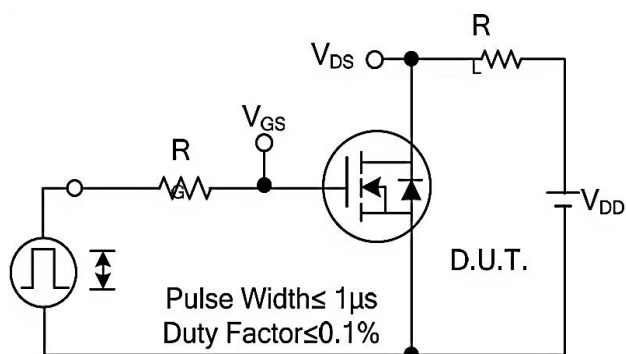




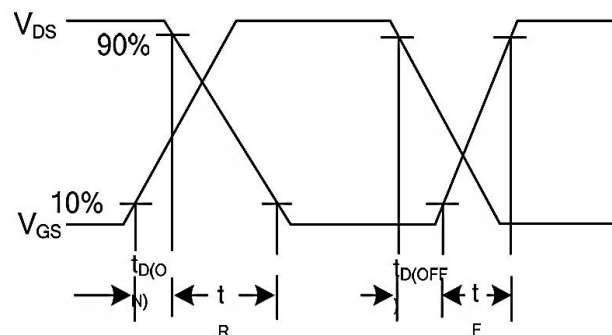
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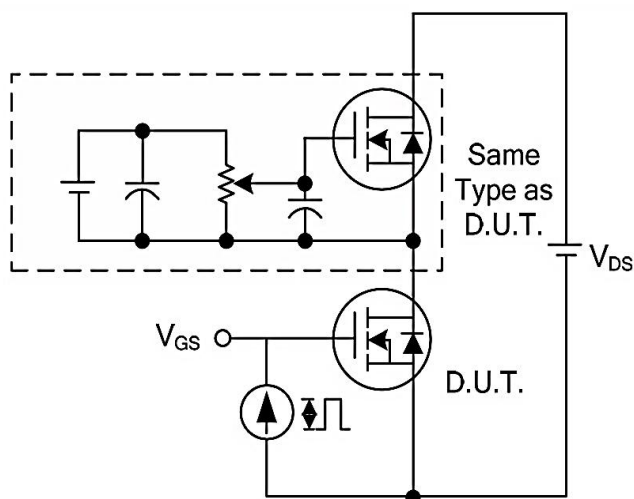
■ TEST CIRCUITS AND WAVEFORMS(Con.t)



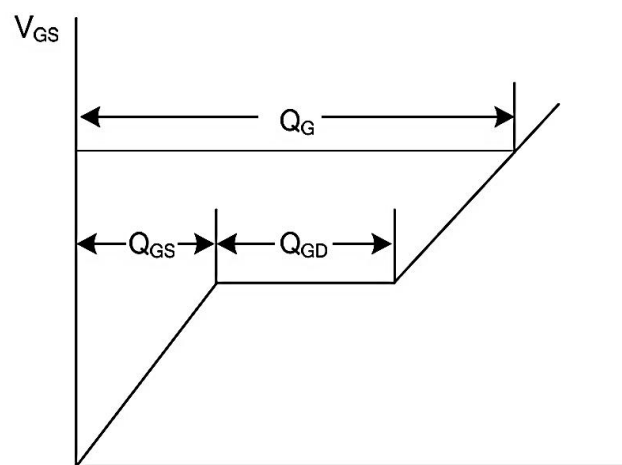
Switching Test Circuit



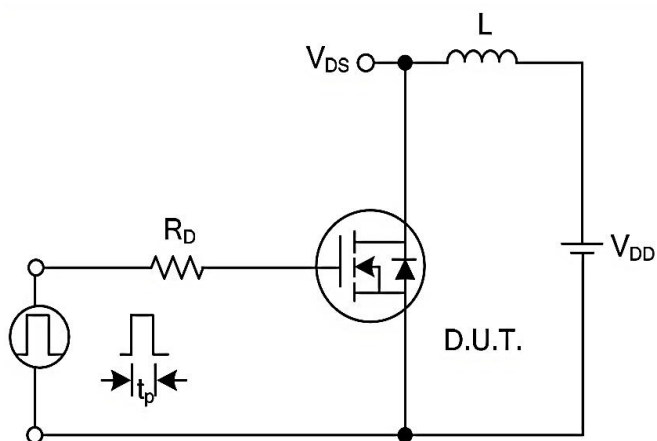
Switching Waveforms



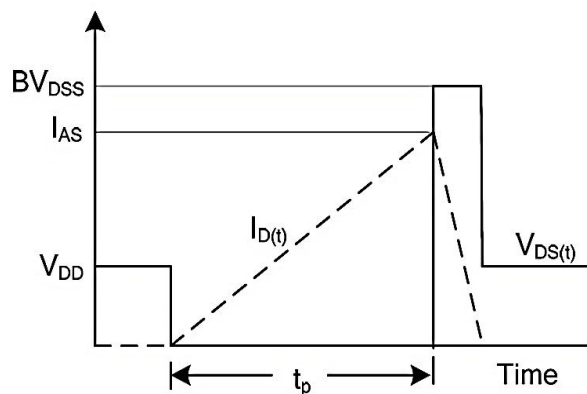
Gate Charge Test Circuit



Charge Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



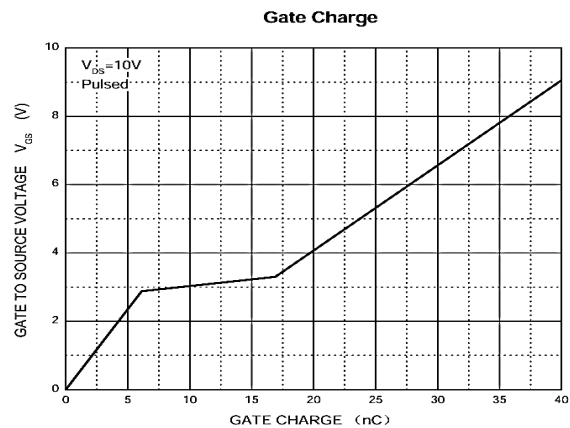
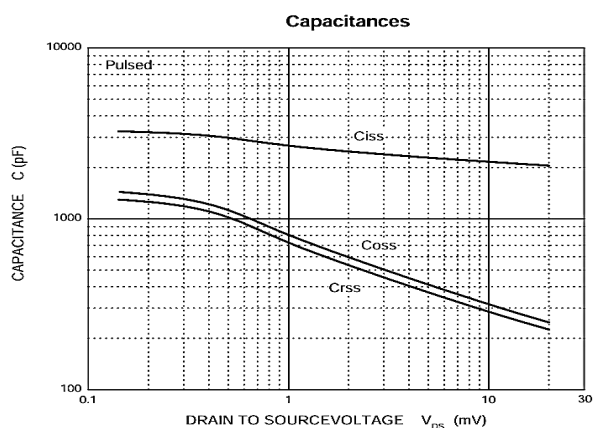
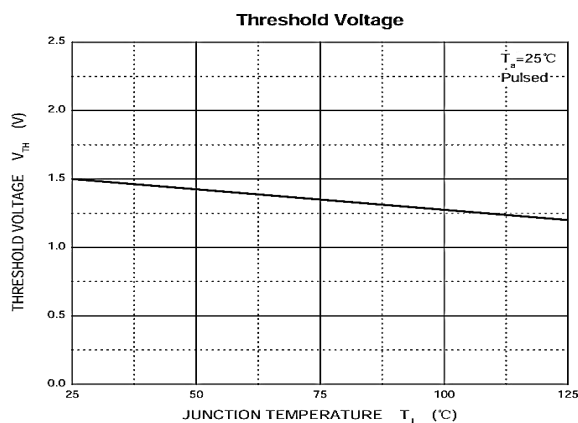
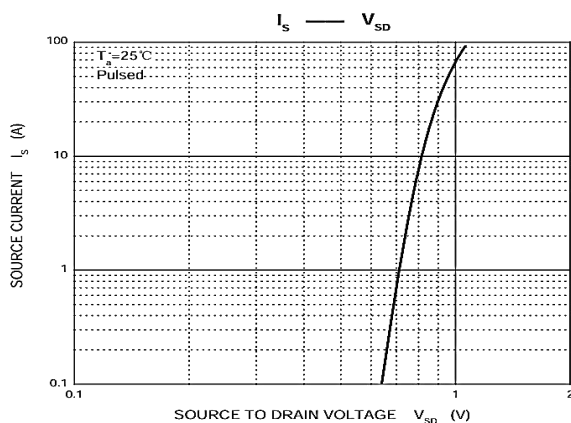
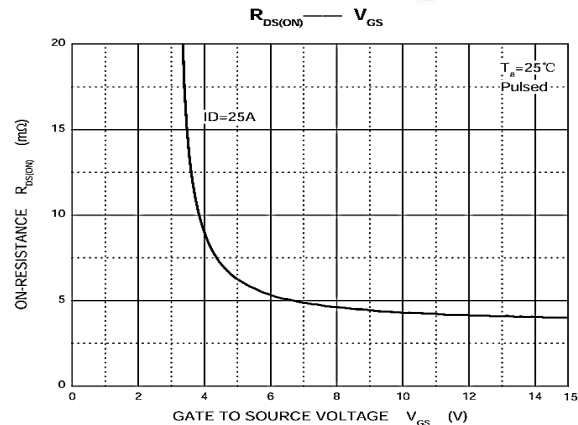
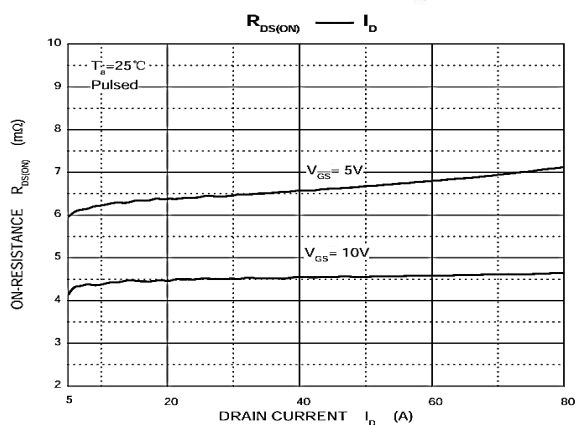
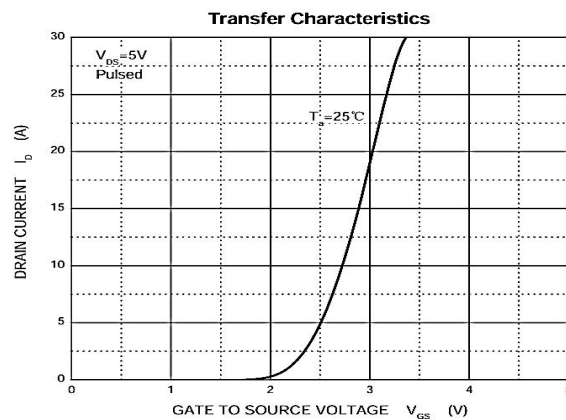
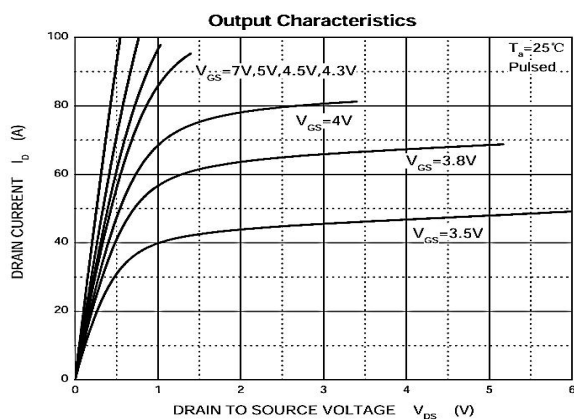
Unclamped Inductive Switching Waveforms



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TYPICAL CHARACTERISTICS

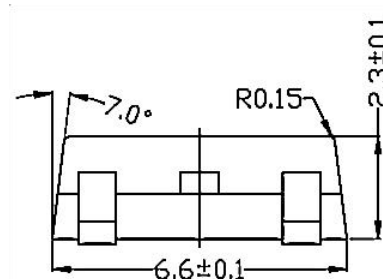
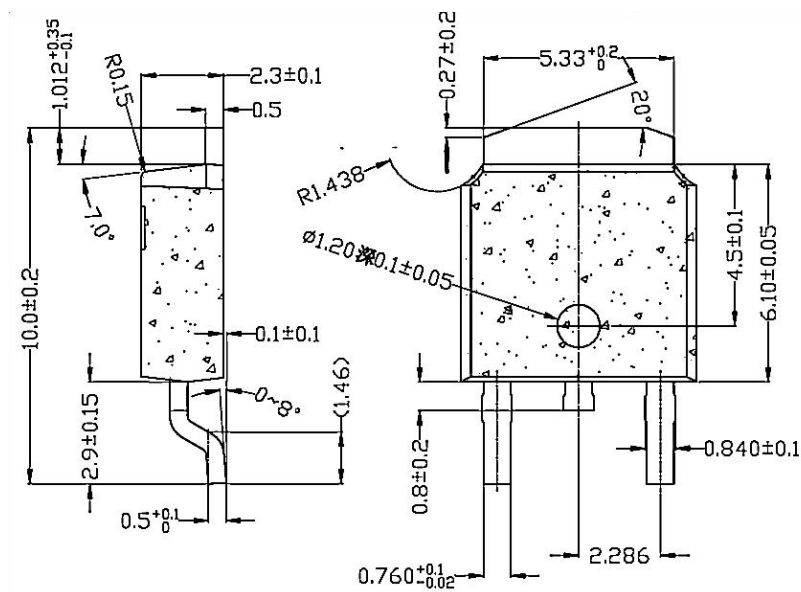




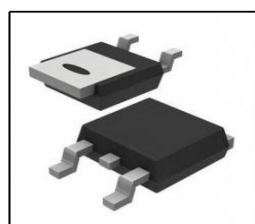
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TO - 252 PACKAGE OUTLINE DIMENSIONS



TO - 252 PACKING INFORMATION



2500PC
S/reel



2 Reel/BOX



Outer box

5 Inner
Box



Inner box

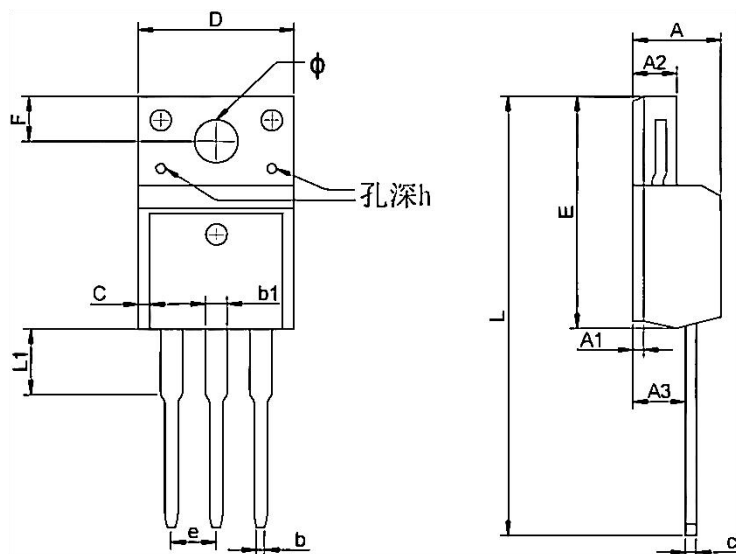
Package version	Reel dimensions $\Phi \times H$ (mm)	Per Reel (pcs)	Reels per box	Inner box dimensions $L \times W \times H$ (mm)	Outer box (pcs)	Outer box dimensions $L \times W \times H$ (mm)
TO-252	$\Phi 330 \times 20$	2500	2	360*340*50	25000	375*375*280



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TO-220F PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max	Min	Max
A	4.300	4.750	0.169	0.185
A1	1.830 REF		0.072 REF	
A2	2.300	2.850	0.090	0.112
A3	2.500	2.900	0.098	0.114
b	0.400	0.420	0.016	0.016
b1	1.220	1.280	0.048	0.050
C	0.690	0.720	0.027	0.028
c	0.490	0.510	0.019	0.020
D	9.960	10.200	0.392	0.400
E	15.000	15.950	0.588	0.625
e	2.574 TYP		0.101TYP	
F	3.470 REF		0.136 REF	
y	3.200 REF		0.125 REF	
h	0.000	0.300	0.000	0.012
L	28.780	28.900	1.128	1.133
L1	2.990	3.100	0.117	0.122

TO - 220F PACKING INFORMATION



50PCS

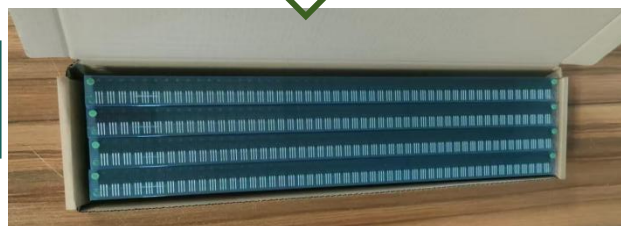


20 Tube



Outer Box

5 Inner
Box



Inner Box

Package version	Tube dimensions LxWxH (mm)	Per Tube (pcs)	Tube per box	Inner box dimensions LxWxH (mm)	PCS/ Inner box	Outer box dimensions LxWxH(mm)	PCS/ Outer box
TO-220F	530*32*7	50	20	580*155*50	1000	602*277*188	5000